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Sheet Title:

TIDA00743 Sheet 4.SchDoc

Version control disabled

Engineer:

Drawn By:

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Mod. Date:

145 mW at 3.3V - 45 ma

Total ON BOARD 3.3 V Current = 150mA

Engineer:

Drawn By:

SVN Rev:

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Assembly Notes:
- ZZ1: This Assembly Note is for PCB labels only.
- ZZ2: These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3: These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4: These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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